



Semiconductor Device Type: H6A 004 VDFN 3.2x5.0x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e4		
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	(mg) Total	Mold Compound	% of Total Weight			
Silica, fused	60676-86-0	Mold Compound	54.567	22.372	545,670	24.86	Silica, fused	60676-86-0	90.00		
Epoxy Resin	Trade Secret	Mold Compound	2.941	1.206	29,406		Epoxy Resin	Trade Secret	4.85		
Phenolic Resin	Trade Secret	Mold Compound	2.941	1.206	29,406		Phenolic Resin	Trade Secret	4.85		
Carbon Black	1333-86-4	Mold Compound	0.182	0.075	1,819		Carbon Black	1333-86-4	0.30		
						Total 100.00					
Copper	7440-50-8	Lead Frame	34.230	14.034	342,301	14.42			35.18		
Iron	7439-89-6	Lead Frame	0.809	0.332	8,091		(mg) Total	Lead Frame		% of Total Weight	
Phosphorous	7723-14-0	Lead Frame	0.088	0.036	880		Copper	7440-50-8		97.30	
Zinc (Metal)	7440-66-6	Lead Frame	0.053	0.022	528		Iron	7439-89-6		2.30	
Silver	7440-22-4	Die Attach	0.375	0.154	3,750	Phosphorous	7723-14-0	0.25	0.21		
Methacrylic acid, isobornyl ester	7534-94-3	Die Attach	0.070	0.029	700	Zinc (Metal)	7440-66-6	0.15			
1,3-Bismaleimidobenzene polymer with oxirane mono-2-propenoate	3006-93-7	Die Attach	0.038	0.015	375			Total 100.00			
Silicon	7440-21-3	Chip (Die)	2.000	0.820	20,000	(mg) Total	Die Attach	% of Total Weight			
Gold	7440-57-5	Wire Bond	0.210	0.086	2,100	Silver	7440-22-4	75.00	0.82		
Nickel	7440-02-0	Plating on external leads (pins)	1.332	0.546	13,320	Methacrylic acid, isobornyl ester	7534-94-3	14.00			
Palladium	7440-05-3	Plating on external leads (pins)	0.074	0.030	740	1,3-Bismaleimidobenzene polymer with oxirane mono-2-prop	3006-93-7	7.50			
Gold	7440-57-5	Plating on external leads (pins)	0.074	0.030	740	1017237-78-3	1017237-78-3	3.50			
TOTALS: 100.000 41.000 1,000,000						Total 100.00					
0.0410 g Total Mass											
								0.82		2.00	
								Total (mg)		Chip (Die)	
								Doped Silicon		7440-21-3	
								Total		100.00	
								0.09		(mg) Total	
								Wire Bond		% of Total Weight	
								Gold		7440-57-5	
								Total		100.00	
								0.61		(mg) Total	
								Plating on external leads (pins)		% of Total Weight	
								Nickel		7440-02-0	
								Palladium		7440-05-3	
								Gold		7440-57-5	
								Total		100.00	
						41.00				100.00	

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at <http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/>

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <http://echa.europa.eu/web/guest/candidate-list-table>